



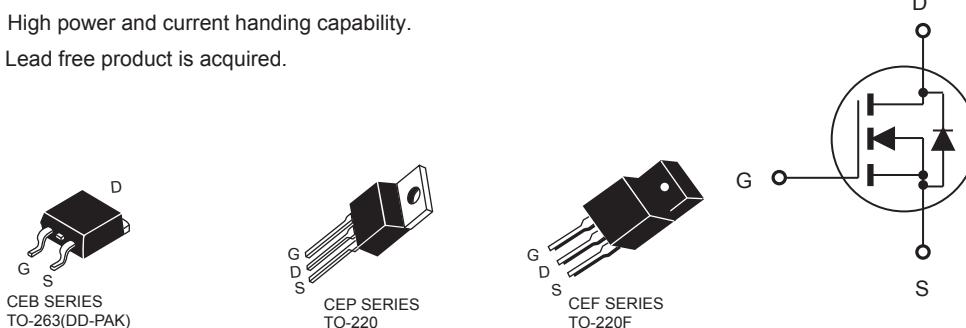
CEP04N7G/CEB04N7G □ CEF04N7G

N-Channel Enhancement Mode Field Effect Transistor

FEATURES

Type	V _{DSS}	R _{DS(ON)}	I _D	@V _{GS}
CEP04N7G	700V	3.3Ω	4A	10V
CEB04N7G	700V	3.3Ω	4A	10V
CEF04N7G	700V	3.3Ω	4A ^d	10V

- Super high dense cell design for extremely low R_{DS(ON)}.
- High power and current handing capability.
- Lead free product is acquired.



ABSOLUTE MAXIMUM RATINGS T_C = 25°C unless otherwise noted

Parameter	Symbol	Limit		Units
		TO-220/263	TO-220F	
Drain-Source Voltage	V _{DS}	700		V
Gate-Source Voltage	V _{GS}	±30		V
Drain Current-Continuous	I _D	4	4 ^d	A
Drain Current-Pulsed ^a	I _{DM} ^e	16	16 ^d	A
Maximum Power Dissipation @ T _C = 25°C - Derate above 25°C	P _D	84 0.67	35 0.28	W W/°C
Operating and Store Temperature Range	T _J , T _{stg}	-55 to 150		°C

Thermal Characteristics

Parameter	Symbol	Limit		Units
Thermal Resistance, Junction-to-Case	R _{θJC}	1.5	3.6	°C/W
Thermal Resistance, Junction-to-Ambient	R _{θJA}	62.5	65	°C/W



CEP04N7G/CEB04N7G □

CEF04N7G

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

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Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	700			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 700\text{V}, V_{\text{GS}} = 0\text{V}$			25	μA
Gate Body Leakage Current, Forward	I_{GSSF}	$V_{\text{GS}} = 30\text{V}, V_{\text{DS}} = 0\text{V}$			100	nA
Gate Body Leakage Current, Reverse	I_{GSSR}	$V_{\text{GS}} = -30\text{V}, V_{\text{DS}} = 0\text{V}$			-100	nA
On Characteristics^b						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	2		4	V
Static Drain-Source On-Resistance	$R_{\text{DS(on)}}$	$V_{\text{GS}} = 10\text{V}, I_D = 2\text{A}$		2.5	3.3	Ω
Dynamic Characteristics^c						
Forward Transconductance	g_{FS}	$V_{\text{DS}} = 40\text{V}, I_D = 1\text{A}$		2		S
Input Capacitance	C_{iss}	$V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		595		pF
Output Capacitance	C_{oss}			80		pF
Reverse Transfer Capacitance	C_{rss}			20		pF
Switching Characteristics^c						
Turn-On Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}} = 300\text{V}, I_D = 4\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 25\Omega$		18	36	ns
Turn-On Rise Time	t_r			17	34	ns
Turn-Off Delay Time	$t_{\text{d(off)}}$			40.5	81	ns
Turn-Off Fall Time	t_f			19	38	ns
Total Gate Charge	Q_g	$V_{\text{DS}} = 480\text{V}, I_D = 4\text{A}, V_{\text{GS}} = 10\text{V}$		14	18.2	nC
Gate-Source Charge	Q_{gs}			3		nC
Gate-Drain Charge	Q_{gd}			6		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current	I_S				2.5	A
Drain-Source Diode Forward Voltage ^b	V_{SD}	$V_{\text{GS}} = 0\text{V}, I_S = 2.5\text{A}$			1.5	V

Notes :

- a.Repetitive Rating : Pulse width limited by maximum junction temperature .
- b.Pulse Test : Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
- c.Guaranteed by design, not subject to production testing.
- d.Limited only by maximum temperature allowed .
- e.Pulse width limited by safe operating area .

CEP

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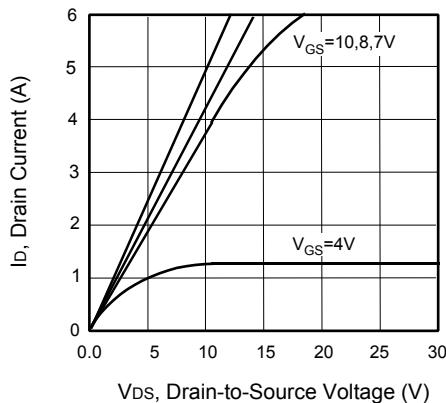


Figure 1. Output Characteristics

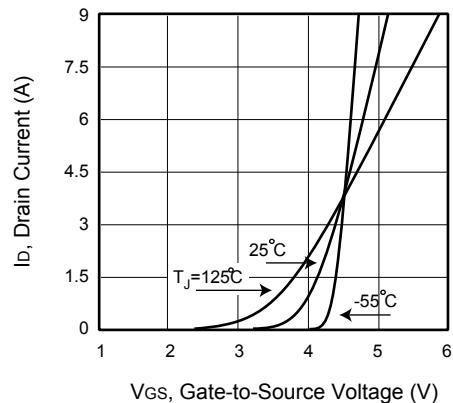


Figure 2. Transfer Characteristics

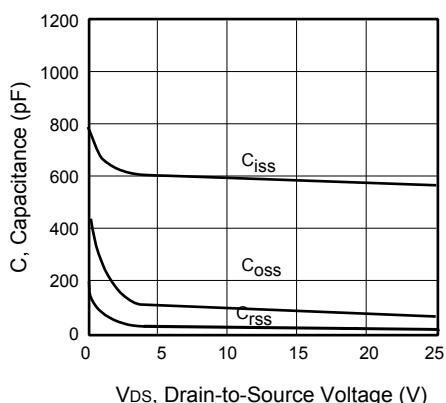


Figure 3. Capacitance

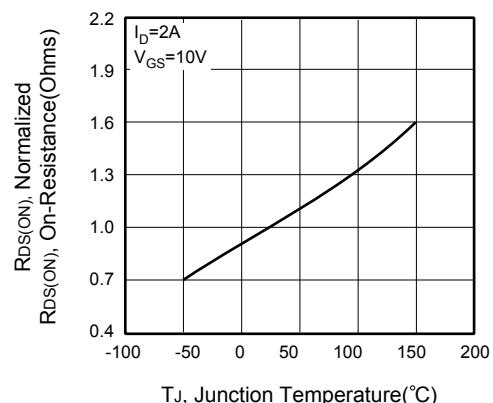


Figure 4. On-Resistance Variation with Temperature

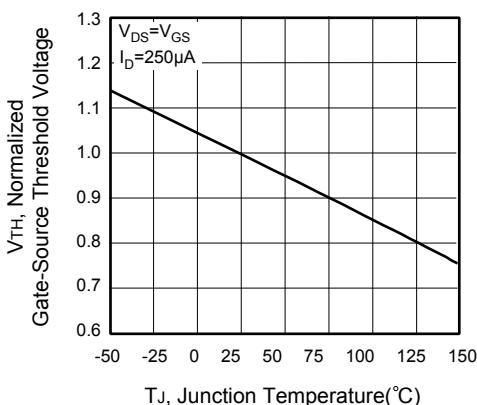


Figure 5. Gate Threshold Variation with Temperature

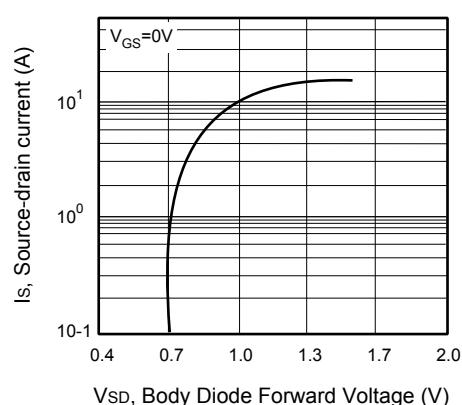


Figure 6. Body Diode Forward Voltage Variation with Source Current

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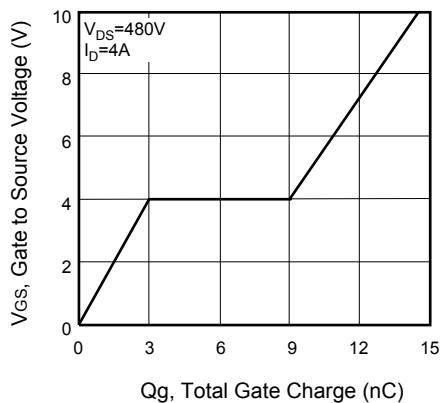


Figure 7. Gate Charge

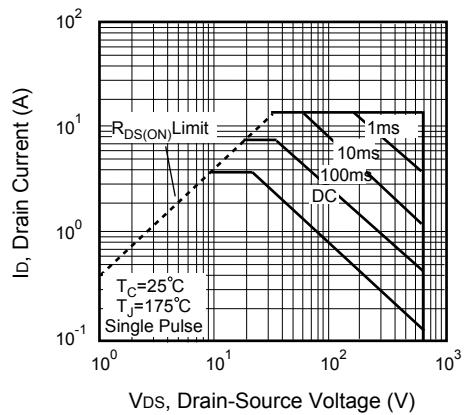


Figure 8. Maximum Safe
Operating Area

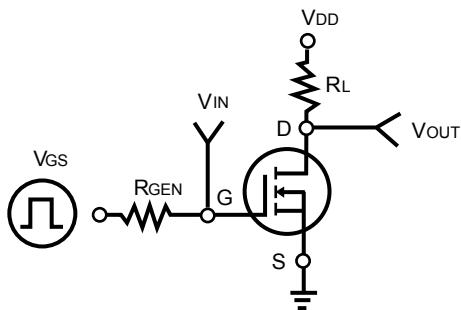


Figure 9. Switching Test Circuit

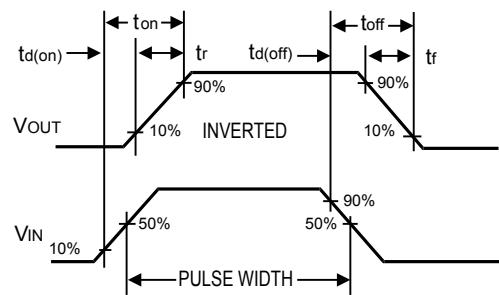


Figure 10. Switching Waveforms

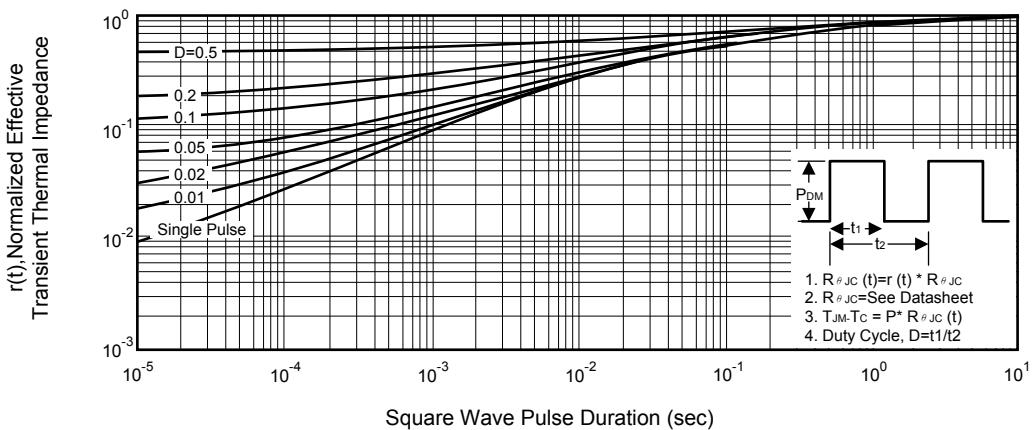


Figure 11. Normalized Thermal Transient Impedance Curve